

RSAM™ Data Sheet RSAM-1560-100ps-x

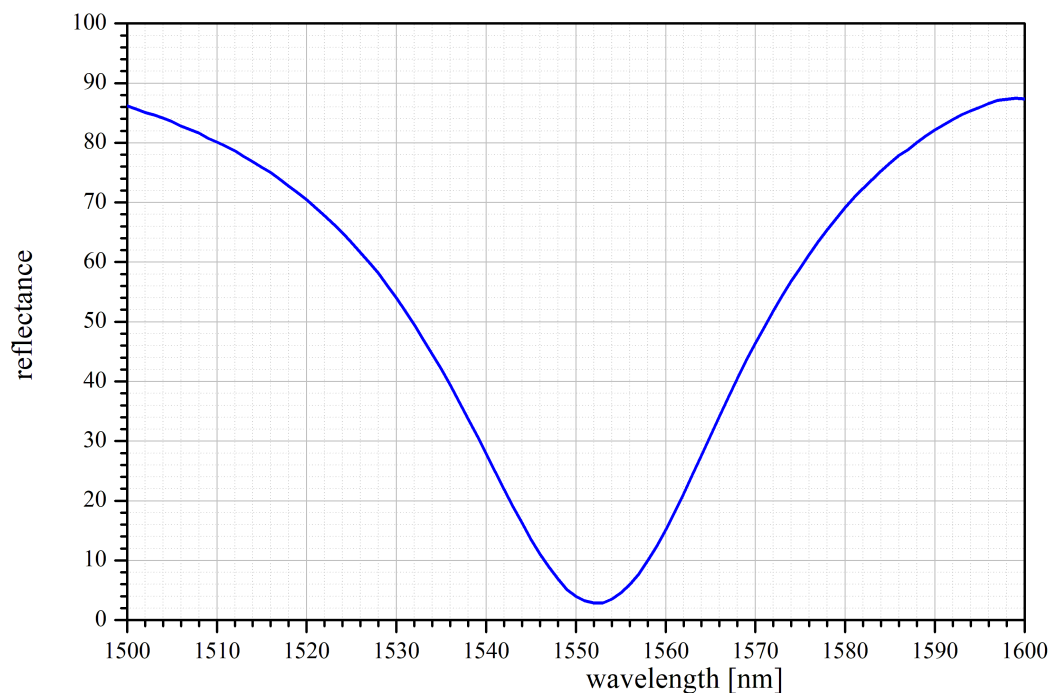
	Minimum	Typical Value	Maximum
Operational wavelength λ_o ¹		1560 nm	
FWHM	10 nm	15nm	
Low intensity absorptance @ λ_o	90 %	95 %	100 %
Low intensity reflectance @ λ_o	0 %	5 %	10 %
Modulation depth ΔR	50 %	75 %	90 %
Non-saturable loss A_{ns} ²	50 %	25 %	10 %
Saturation fluence Φ_{sat}	10 $\mu\text{J}/\text{cm}^2$	20 $\mu\text{J}/\text{cm}^2$	30 $\mu\text{J}/\text{cm}^2$
Relaxation time constant τ	50 ps	~ 100 ps	150 ps
Damage threshold Φ		800 $\mu\text{J}/\text{cm}^2$	
Absorber Peak Temperature			150°C ³
Chip thickness	425 μm	450 μm	475 μm
Protection	SAM is protected with a dielectric front layer		

¹ angle and temperature dependent

² depending on the pulse duration

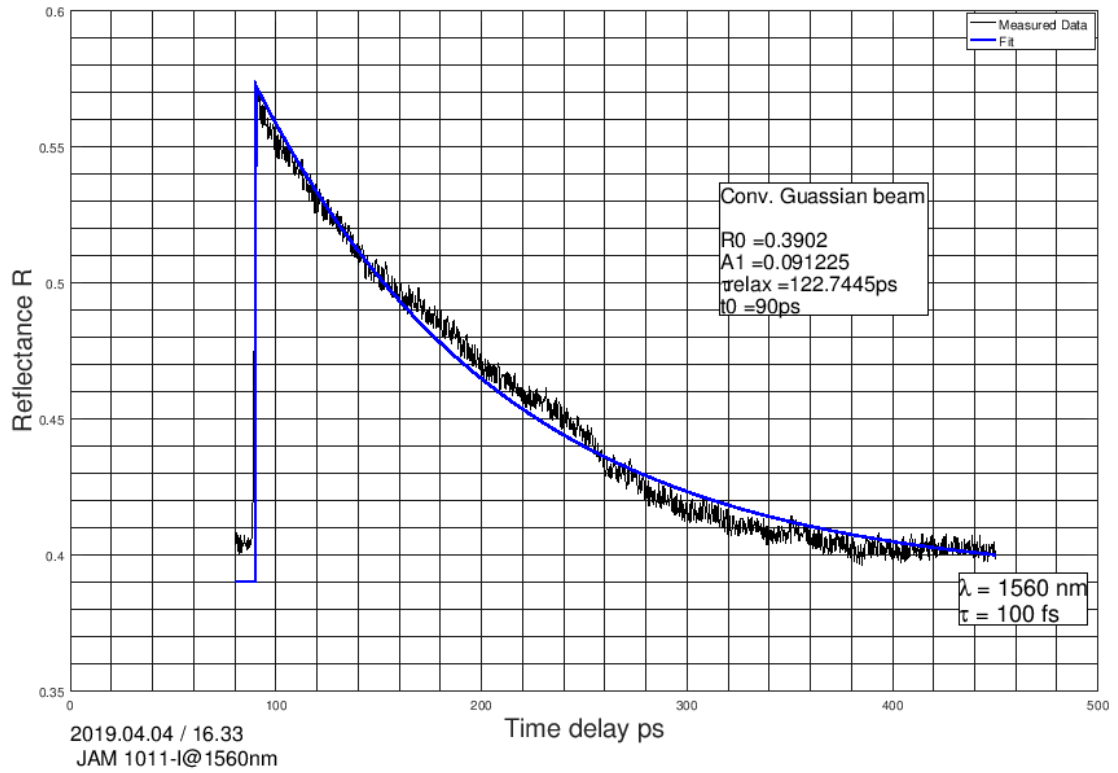
³ Please make sure that this temperature is not exceeded in pulsed operation shortly after the optical pulse.

Unsaturated spectral reflectance, measured at room temperature with 6° AOI

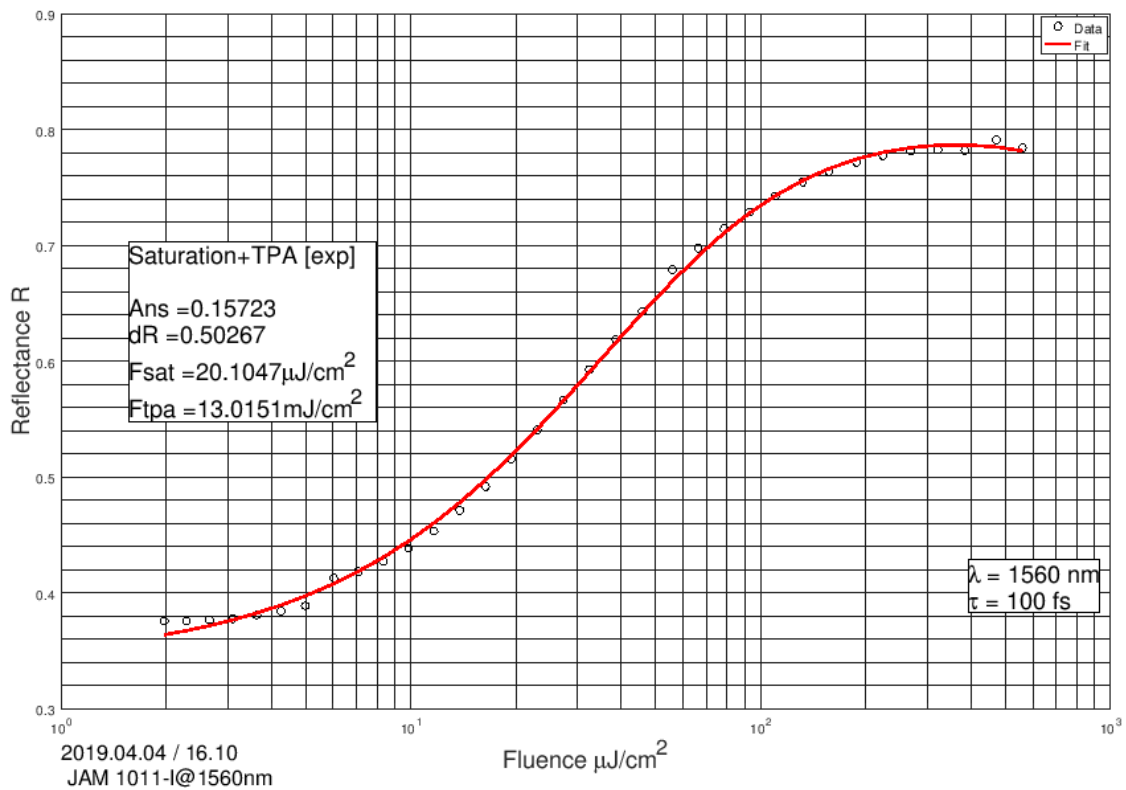


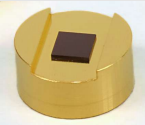
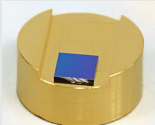
JAM 1011-I

Relaxation time



Saturation measurement



Mounting Options RSAM-1560-100ps-x	Description
x = 4.0-0	Single chip, unmounted, chip size 4.0mm x 4.0mm
x = 1.0b-0	Batch of 4 unmounted chips, chip size 1.0mm x 1.0mm
x = 1.3b-0	Batch of 4 unmounted chips, chip size 1.3mm x 1.3mm
x = 4.0-12.7g-c / 4.0-12.7g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 12.7 mm \varnothing
x = 4.0-25.0g-c / 4.0-25.0g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.0 mm \varnothing
x = 4.0-25.4g-c / 4.0-25.4g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.4 mm \varnothing
x = 4.0-12.7s-c / 4.0-12.7s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 12.7 mm \varnothing
x = 4.0-25.0s-c / 4.0-25.0s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.0 mm \varnothing
x = 4.0-25.4s-c / 4.0-25.4s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.4 mm \varnothing
x = 4.0-25.0w-c / 4.0-25.0w-e	chip size 4.0mm x 4.0mm, soldered on a water cooled copper heat sink with 25.0 mm diameter
x = 4.0-25.4h-c / 4.0-25.4h-e	chip size 4.0mm x 4.0mm, thin film soldered on a water cooled copper heat sink with 25.0 mm diameter for high power application
-c Center mounting 	-e Edge mounting 
x = FC/PC / FC/APC with TEC	mounted on a 1 m monomode fiber cable with FC/PC / FC/APC connector and TEC (thermoelectric cooler) for fine tuning of the resonance wavelength available fiber types: HI 980, HI 1060, Fujikura SM98-PS-U25A (polarisation maintaining (PM) fiber)
Other chip dimensions are also possible, please ask.	